

# MINI MELF Glass-Encapsulate Diodes

Small Signal Fast Switching Diodes

## Features

- $V_R$  50-200V
- $I_F$  250mA

## Applications

- Extreme fast switches

**MINI MELF(SOD-80/ LL- 34)**



## Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	BAV			
				100	101	102	103
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		50	100	150	200
Repetitive Peak Reverse Voltage	$V_R$	V		60	120	200	250
Forward current	$I_F$	mA	60Hz Half-sine wave, Resistance load, $T_a=25^\circ C$			250	
Surge(Non-repetitive)Forward Current	$I_{FSM}$	A	60Hz Half-sine wave, 1 cycle, $T_a=25^\circ C$			1	
Junction Temperature	$T_J$	°C			-55~+175		
Storage Temperature	$T_{STG}$	°C			-55 ~ +175		
Power Dissipation	$P_{tot}$	mW				400	

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**Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

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Item	Symbol	Unit	Test Condition		Max
Peak Forward Voltage	$V_{FM}$	V	$I_{FM}=1\text{00 mA}$ $I_{FM}=2\text{00 mA}$		1.00 1.25
Peak Reverse Current	$I_{RRM}$	uA	$V_{RM}=V_R$	$T_a=25^\circ\text{C}$	0.1
Reverse recovery time	$t_{rr}$	ns	$IF=30\text{mA}$ to $IR=30\text{mA}$ , $I_{rr}=3\text{mA}, RL=100\Omega$		50
Diode capacitance	$C_d$	pF	$VR=0, f=1\text{MHZ}$		5

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## Typical Characteristics

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Figure 1. Reverse Current vs. Junction Temperature

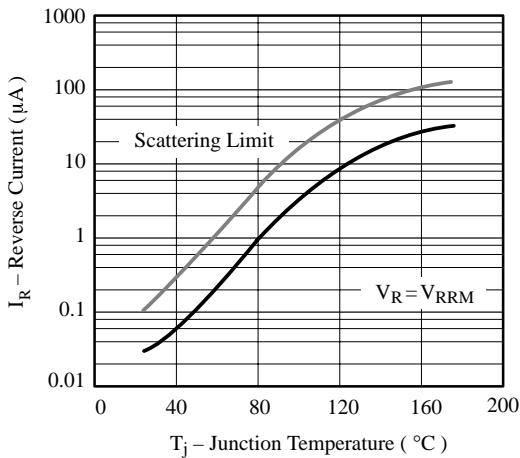


Figure 2. Forward Current vs. Forward Voltage

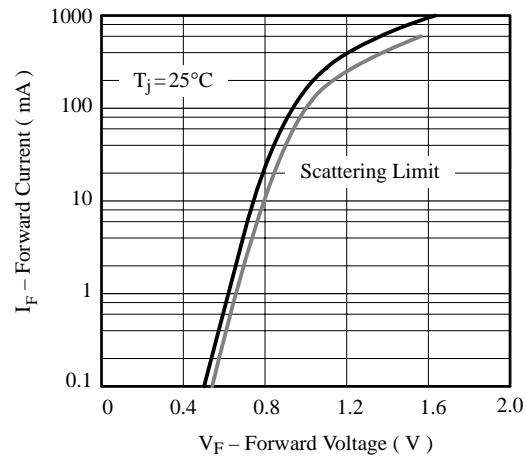
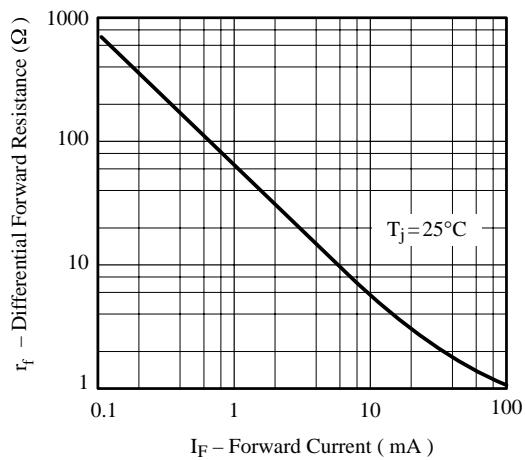
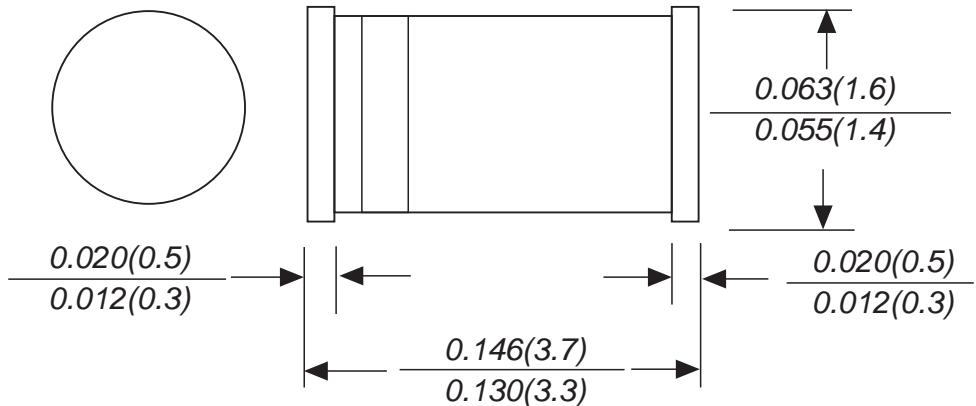


Figure 3. Differential Forward Resistance vs. Forward Current

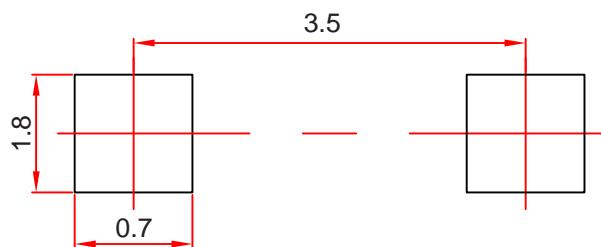


## MINI MELF Package Outline Dimensions



Dimensions in millimeters

## MINI MELF Suggested Pad Layout



### Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.

### NOTICE

JSHD reserve the right to make modifications,enhancements, improvements, corrections or other changes without further notice to any product herein .JSHD does not assume any liability arising out of the application or use of any product described herein.

## Packaging Specifications for Surface Mounted Glass Diodes

1. The method of packaging and dimension are shown as below figure. (Dimension in mm)

